

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

	PRODUC'	T/PROCES	S CE	IANGE NO	TICE (PC	CN)	
PCN #: A170 Product Affected		DATE: 22-Sep	-2017	MEANS OF DIS  □ Product Mark ■ Back Mark □ Date Code □ Other	Lot # will hav	CHANGED DEVICES: re: or ASECL, Taiwan	
Date Effective:	22-Dec-2017						
Contact:	IDT PCN DESK			Attachment:	Yes	☐ No	
E-mail:	pcndesk@idt.com				contact your loca e request.	l sales representative for	
DESCRIPTION	AND PURPOSE OF (	CHANGE:					
<ul> <li>□ Die Technology</li> <li>□ Wafer Fabrication Process</li> <li>□ Assembly Process</li> <li>□ Equipment</li> <li>□ Material</li> </ul>		This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.  There is no change to the moisture performance.					
☐ Testing ☐ Manufacturing ☐ Data Sheet ☐ Other	g Site	Attachment I deta	ils the q	ualification results			
	QUALIFICATION SU ation data shown in Atta						
IDT records indito grant approvation it will be assume IDT reserves the	cknowledGMENT cate that you require will or request additional in that this change is accertished to ship either versus in has been depleted.	ritten notification of nformation. If IDT of ceptable. sion manufactured a	loes not	receive acknowled	dgement within 30	days of this notice	
Customer:				] Approval fo	or shipments p	rior to effective date.	
Name/Date:			E-	Mail Address:			
Title:			Pł	none#/Fax#:			
CUSTOMER CO				•			
IDT ACKNOW	LEDGMENT OF REC	TEIDT.					
	LEDGMENT OF REC			DATE:			

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# PRODUCT/PROCESS CHANGE NOTICE (PCN)

### **ATTACHMENT I - PCN # : A1709-03**

PCN Type: Manufacturing Site - Alternate Assembly Location

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

#### **Detail Of Change:**

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (UTL, Thailand)	Alternate Assembly (ASECL, Taiwan)	
Die Attach	8600	EN4900G	
Bond Wire	Copper Wire	Copper Wire	
Mold Compound	G700LTD	G700LA	

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### **ATTACHMENT I - PCN # : A1709-03**

## **Qualification Information and Qualification Data:**

**Affected Packages:** VFQFPN-68

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** VFQFPN-68

Tost Dosavintion	Test Method	Test Results (Rej / SS)			
Test Description	Test Wiethod	Lot 1	Lot 2	Lot 3	
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25	
* HAST - biased (110 °C/85% RH, 264 Hrs)	JESD22-A110	0/25	0/25	0/25	
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25	
Ball Shear Test	JESD22-B116	0/5	0/5	0/5	
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5	
X Ray	IDT Spec. MAC- 3012	0/45	0/45	0/45	
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-	

<sup>\*</sup> Tests were subjected to Preconditioning per JESD22-A113 prior to stress test